Express Mail No. EK985527007US

Practitioner's Docket No. P-1000

Preliminary Classification:

Proposed Class:

Subclass:

NOTE: "All applicants are requested to include a preliminary classification on newly filed patent applications. The preliminary classification, preferably class and subclass designations, should be identified in the upper right-hand comer of the letter of transmittal accompanying the application papers, for example 'Proposed Class 2, subclass 129.' " M.P.E.P. § 601, 7th ed.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application Assistant Commissioner for Patents Washington, D.C. 20231

NEW APPLICATION TRANSMITTAL

Transmitted herewith for filing is the patent application of

Stefan O. Dick; Michelle B. Martin; Roger Nobilet; Frederic Bouvier Inventor(s):

WARNING: 37 C.F.R. § 1.41(a)(1) points out:

"(a) A patent is applied for in the name or names of the actual inventor or inventors.

"(1) The inventorship of a nonprovisional application is that inventorship set forth in the oath or declaration as prescribed by § 1.63, except as provided for in § 1.53(d)(4) and § 1.63(d). If an oath or declaration as prescribed by § 1.63 is not filed during the pendency of a nonprovisional application, the inventorship is that inventorship set forth in the application papers filed pursuant to § 1.53(b), unless a petition under this paragraph accompanied by the fee set forth in § 1.17(i) is filed supplying or changing the name or names of the inventor or inventors."

For (title):

PACKAGING CONTAINER FOR ELECTRONIC COMPONENTS

CERTIFICATION UNDER 37 C.F.R. § 1.10*

(Express Mail label number is mandatory.) (Express Mail certification is optional.)

I hereby certify that this New Application Transmittal and the documents referred to as attached therein are being (lug. 28, 2000 deposited with the United States Postal Service on this date ____ EK985527007US as "Express Mail Post Office to Addressee," mailing Label Number _ dressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231.

Dorothy Goodlett

(type or print name of person mailing paper)

Signature of person mailing paper

WARNING: Certificate of mailing (first class) or facsimile transmission procedures of 37 C.F.R. § 1.8 cannot be used to obtain a date of mailing or transmission for this correspondence.

*WARNING: Each paper or fee filed by "Express Mail" must have the number of the "Express Mail" mailing label placed thereon prior to mailing. 37 C.F.R. § 1.10(b).

> "Since the filing of correspondence under § 1.10 without the Express Mail mailing label thereon is an oversight that can be avoided by the exercise of reasonable care, requests for waiver of this requirement will not be granted on petition." Notice of Oct. 24, 1996, 60 Fed. Reg. 56,439, at 56,442.

> > (New Application Transmittal [4-1]-page 1 of 11)

1.	Туре	of	Applicat	ior
----	------	----	----------	-----

This new	ap	plication	is	for	a(n))
----------	----	-----------	----	-----	------	---

,	(check one applicable item below)
	Original (nonprovisional)
	Design
[☐ Plant
WARNING:	Do not use this transmittal for a completion in the U.S. of an International Application under 35 U.S.C. § 371(c)(4), unless the International Application is being filed as a divisional, continuation or continuation-in-part application.
WARNING:	Do not use this transmittal for the filing of a provisional application.
TRA	ne of the following 3 items apply, then complete and attach ADDED PAGES FOR NEW APPLICATION ANSMITTAL WHERE BENEFIT OF A PRIOR U.S. APPLICATION CLAIMED and a NOTIFICATION PARENT APPLICATION OF THE FILING OF THIS CONTINUATION APPLICATION.
	Divisional.
	Continuation.
	Continuation-in-part (C-I-P).
. Benefit	of Prior U.S. Application(s) (35 U.S.C. 88 119(e), 120, or 121)

2.

NOTE: A nonprovisional application may claim an invention disclosed in one or more prior filed copending nonprovisional applications or copending international applications designating the United States of America. In order for a nonprovisional application to claim the benefit of a prior filed copending nonprovisional application or copending international application designating the United States of America, each prior application must name as an inventor at least one inventor named in the later filed nonprovisional application and disclose the named inventor's invention claimed in at least one claim of the later filed nonprovisional application in the manner provided by the first paragraph of 35 U.S.C. § 112. Each prior application must also be:

- (i) An international application entitled to a filing date in accordance with PCT Article 11 and designating the United States of America; or
 - (ii) Complete as set forth in § 1.51(b); or
- (iii) Entitled to a filing date as set forth in § 1.53(b) or § 1.53(d) and include the basic filing fee set forth in § 1.16; or
- (iv) Entitled to a filing date as set forth in § 1.53(b) and have paid therein the processing and retention fee set forth in § 1.21(I) within the time period set forth in § 1.53(f).

37 C.F.R. § 1.78(a)(1).

NOTE: If the new application being transmitted is a divisional, continuation or a continuation-in-part of a parent case, or where the parent case is an International Application which designated the U.S., or benefit of a prior provisional application is claimed, then check the following item and complete and attach ADDED PAGES FOR NEW APPLICATION TRANSMITTAL WHERE BENEFIT OF PRIOR U.S. APPLICA-TION(S) CLAIMED.

WARNING: If an application claims the benefit of the filing date of an earlier filed application under 35 U.S.C. §§ 120, 121 or 365(c), the 20-year term of that application will be based upon the filing date of the earliest U.S. application that the application makes reference to under 35 U.S.C. §§ 120, 121 or 365(c). (35 U.S.C. § 154(a)(2) does not take into account, for the determination of the patent term, any application on which priority is claimed under 35 U.S.C. §§ 119, 365(a) or 365(b).) For a c-i-p application, applicant should review whether any claim in the patent that will issue is supported by an earlier application and, if not, the applicant should consider canceling the reference to the earlier filed application. The term of a patent is not based on a claim-by-claim approach. See Notice of April 14, 1995, 60 Fed. Reg. 20,195, at 20,205.

(New Application Transmittal [4-1]—page 2 of 11)

WARNIN	h P	When the last day of pendency of a provisional application falls on a Saturday, Sunday, or Federal oliday within the District of Columbia, any nonprovisional application claiming benefit of the rovisional application must be filed prior to the Saturday, Sunday, or Federal holiday within the istrict of Columbia. See 37 C.F.R. § 1.78(a)(3).
	tio	e new application being transmitted claims the benefit of prior U.S. applican(s). Enclosed are ADDED PAGES FOR NEW APPLICATION TRANSMITTAL HERE BENEFIT OF PRIOR U.S. APPLICATION(S) CLAIMED.
3. Pape	ers E	nclosed
		ed for filing date under 37 C.F.R. § 1.53(b) (Regular) or 37 C.F.R. § 1.153) Application
<u>24</u> F	ages	s of specification
4_ F	ages	s of claims
<u>6</u> 8	Sheet	s of drawing
WARNIN	fill sr dr th Fo	O NOT submit original drawings. A high quality copy of the drawings should be supplied when ing a patent application. The drawings that are submitted to the Office must be on strong, white, mooth, and non-shiny paper and meet the standards according to § 1.84. If corrections to the rawings are necessary, they should be made to the original drawing and a high-quality copy of the corrected original drawing then submitted to the Office. Only one copy is required or desired. For comments on proposed then-new 37 C.F.R. § 1.84, see Notice of March 9, 1988 (1990 O.G. 7-62).
ti c	nvento he Off on the	fying indicia, if provided, should include the application number or the title of the invention, or's name, docket number (if any), and the name and telephone number of a person to call if ice is unable to match the drawings to the proper application. This information should be placed back of each sheet of drawing a minimum distance of 1.5 cm. (5/8 inch) down from the top page" 37 C.F.R. § 1.84(c)).
		(complete the following, if applicable)
	"PE	e enclosed drawing(s) are photograph(s), and there is also attached a ETITION TO ACCEPT PHOTOGRAPH(S) AS DRAWING(S)." C7 C.F.R84(b).
	for	mal
豆	info	ormal
B. Oth	ner P	apers Enclosed
8_ P	ages	of declaration and power of attorney
P	ages	of abstract
C	ther	
. Addit	ional	papers enclosed
	Am	endment to claims
		Cancel in this applications claims before calculating the filing fee. (At least one original independent claim must be retained for filing purposes.)
		Add the claims shown on the attached amendment. (Claims added have been numbered consecutively following the highest numbered original claims.)
	Pre	liminary Amendment
	Info	rmation Disclosure Statement (37 C.F.R. § 1.98)
		m PTO-1449 (PTO/SB/08A and 08B)
	Cita	tions

(New Application Transmittal [4-1]—page 3 of 11)

5.

]	Declaration of Biological Deposit
]	Submission of "Sequence Listing," computer readable copy and/or amendment pertaining thereto for biotechnology invention containing nucleotide and/or amino acid sequence.
	Authorization of Attomey(s) to Accept and Follow Instructions from Representive	
]	Special Comments
]	Other
. Dec	lar	ration or oath (including power of attorney)
NOTE:	the by ap the by be de pe	newly executed declaration is not required in a continuation or divisional application provided that e prior nonprovisional application contained a declaration as required, the application being filed is all or fewer than all the inventors named in the prior application, there is no new matter in the eplication being filed, and a copy of the executed declaration filed in the prior application (showing a signature or an indication thereon that it was signed) is submitted. The copy must be accompanied a statement requesting deletion of the names of person(s) who are not inventors of the application sing filed. If the declaration in the prior application was filed under § 1.47, then a copy of that accompanied by a copy of the decision granting § 1.47 status or, if a nonsigning erson under § 1.47 has subsequently joined in a prior application, then a copy of the subsequently recuted declaration must be filed. See 37 C.F.R. §§ 1.63(d)(1)–(3).
NOTE:	is ab	declaration filed to complete an application must be executed, identify the specification to which it directed, identify each inventor by full name including family name and at least one given name, without breviation together with any other given name or initial, and the residence, post office address and buntry or citizenship of each inventor, and state whether the inventor is a sole or joint inventor. 37 F.R. § 1.63(a)(1)–(4).
NOTE:	as as is thi	The inventorship of a nonprovisional application is that inventorship set forth in the oath or declaration prescribed by § 1.62, except as provided for in § 1.53(d)(4) and § 1.63(d). If an oath or declaration prescribed by § 1.63 is not filed during the pendency of a nonprovisional application, the inventorship that inventorship set forth in the application papers filed pursuant to § 1.53(b), unless a petition under is paragraph accompanied by the fee set forth in § 1.17(f) is filed supplying or changing the name names of the inventor or inventors." 37 C.F.R. § 1.41(a)(1).
V	1	Enclosed
		Executed by
		(check all applicable boxes)
		inventor(s).
		legal representative of inventor(s). 37 C.F.R. §§ 1.42 or 1.43.
		joint inventor or person showing a proprietary interest on behalf of inventor who refused to sign or cannot be reached.
		☐ This is the petition required by 37 C.F.R. § 1.47 and the statement required by 37 C.F.R. § 1.47 is also attached. See item 13 below for fee.
]	Not Enclosed.
NOTE:	th: ma	here the filing is a completion in the U.S. of an International Application or where the completion of e U.S. application contains subject matter in addition to the International Application, the application ay be treated as a continuation or continuation-in-part, as the case may be, utilizing ADDED PAGE OR NEW APPLICATION TRANSMITTAL WHERE BENEFIT OF PRIOR U.S. APPLICATION CLAIMED.
		Application is made by a person authorized under 37 C.F.R. § 1.41(c) on behalf of all the above named inventor(s).
		(Now Application Transmitted Ed. 41 mags 4 of 11)

(New Application Transmittal [4-1]—page 4 of 11)

(The declaration or oath, along with the surcharge required by 37 C.F.R. § 1.16(e) can be filed subsequently).	
Showing that the filing is authorized. (not required unless called into question. 37 C.F.R. § 1.41(d))	
8. Inventorship Statement	
WARNING: If the named inventors are each not the inventors of all the claims an explanation, including the ownership of the various claims at the time the last claimed invention was made, should be submitted.	
The inventorship for all the claims in this application are:	
The same.	
or	
 Not the same. An explanation, including the ownership of the various claims at the time the last claimed invention was made, 	
is submitted.	
☐ will be submitted.	
7. Language	
NOTE: An application including a signed oath or declaration may be filed in a language other than English. An English translation of the non-English language application and the processing fee of \$130.00 required by 37 C.F.R. § 1.17(k) is required to be filed with the application, or within such time as may be set by the Office. 37 C.F.R. § 1.52(d).	
☑ English	
☐ Non-English	
☐ The attached translation includes a statement that the translation is accurate. 37 C.F.R. § 1.52(d).	
3. Assignment	
An assignment of the invention toSud-Chemie Performance Packaging, Inc.	•
101 Christine Drive, Rio Grande Ind. Park, Belen, NM 87002	
is attached. A separate ☑ "COVER SHEET FOR ASSIGNMENT (DOCUMENT) ACCOMPANYING NEW PATENT APPLICATION" or □ FORM PTO 1595 is also attached.	
☐ will follow.	
NOTE: "If an assignment is submitted with a new application, send two separate letters-one for the application and one for the assignment." Notice of May 4, 1990 (1114 O.G. 77-78).	
WARNING: A newly executed "CERTIFICATE UNDER 37 C.F.R. § 3.73(b)" must be filed when a continuation-in-part application is filed by an assignee. Notice of April 30, 1993, 1150 O.G. 62-64.	

(New Application Transmittal [4-1]—page 5 of 11)

9. Certified Copy

Country	Appln. No.		Filed
Country	Appln. No.		Filed
Country	Appin. No.		Filed
rom which priority is claimed			
☐ is (are) attached.			
☐ will follow.			
NOTE: The foreign application forming declaration. 37 C.F.R. § 1.55	ng the basis for the clain (a) and 1.63.	n for priority must	be referred to in the oath or
NOTE: This item is for any foreign pu U.S. application or Internation § 120 is itself entitled to priori PAGES FOR NEW APPLICAT CLAIMED.	al Application from which ty from a prior foreign ap	n this application cl plication, then con	aims benefit under 35 U.S.C. splete item 18 on the ADDED
10. Fee Calculation (37 C.F.R	. § 1.16)		
A. Regular application			
	CLAIMS AS FILE	D	
Number filed	Number Extra	Rate	Basic Fee 37 C.F.R. § 1.16(a) \$760000 \$690
Fotal Claims (37 C.F.R. § 1.16(c)) 21 – 20) = 1	× \$ 18.00	\$18.00
ndependent	<u> </u>	Α Ψ 10.00	Ψ10.00
Claims (37 C.F.R.	_ 1	× \$ 78.00	\$78.00
Multiple dependent claim(s), if any (37 C.F.R. § 1.16(d))	-	+ \$260.00	
☐ Amendment cancelling	g extra claims is er	iclosed.	
☐ Amendment deleting			l.
☐ Fee for extra claims i	s not being paid at	this time.	
NOTE: If the fees for extra claims are n prior to the expiration of the t	ime period set for respo	t be paid or the clair nse by the Patent a	ms cancelled by amendment, and Trademark Office in any
notice of fee deficiency. 37 C.	.r.n. y 1.10(u).		
notice of fee deficiency. 37 C.	ng Fee Calculation		\$ 786.00
notice of fee deficiency. 37 C.	ng Fee Calculation		\$ 786.00

(New Application Transmittal [4-1]—page 6 of 11)

	Plant application (\$480.00—37 C.F.R.	§ 1.16(g))	
		ling fee calculation	\$
11. Small	Entity Statement(s)		,
	Statement(s) that this is (are) attached.	is a filing by a small en	tity under 37 C.F.R. § 1.9 and 1.27
WARNING:	the status is available an affect any other application indirectly dependent upor refiling of an application a continued prosecution a new determination as trapplication. A nonprovision 365(c) of a prior application or in the patter reference to the statem statement in the prior application. The payment of the statem of the statem of the statem of the payment of the statem.	and desired. Status as a small ation or patent, including appoint the application or patent in under § 1.53 as a continuation application under § 1.53(d)), to continued entitlement to small application claiming beration, or a reissue application ent if the nonprovisional application or in the patent and polication or in the patent and	shed in each application or patent in which entity in one application or patent does not plications or patents which are directly or which the status has been established. The m, division, or continuation-in-part (including or the filing of a reissue application requires nall entity status for the continuing or reissue effit under 35 U.S.C. § 119(e), 120, 121, or may rely on a statement filed in the priorication or the reissue application includes a or in the patent or includes a copy of the distatus as a small entity is still proper and or filing fee will be treated as such a reference
WARNING:	"Small entity status must can unequivocally make 1996 (emphasis added).	not be established when the parties the required self-certification	person or persons signing the statement n." M.P.E.P., § 509.03, 6th ed., rev. 2, July
	(comp	lete the following, if ap	plicable)
	Status as a small en	tity was claimed in prio	or application
-	/	, filed on	, from which benefit
į:		this application under:	
	35 U.S.C. § ☐ 11		
	☐ 12 ☐ 12	•	
		55(c),	
	and which status as	s a small entity is still p	proper and desired.
		tatement in the prior a	
		ation (50% of A, B or C	
		\$	•
are	excess of the full fee paid filed within 2 months of a ndable under § 1.136. 37	the date of timely payment of	iy status is established and a refund request of a full fee. The two-month period is not
12. Reque	st for International-	Type Search (37 C.F.F	R. § 1.104(d))
		(complete, if applicable	e)
□ F W	rlease prepare an inte rhen national examin	emational-type search re lation on the merits tak	eport for this application at the time ses place.

13. Fe	e Payr	nent Being Made at This Time		
[☐ Not	Enclosed		
		No filing fee is to be paid at this time. (This and the surcharge required by 37 C.F.R. subsequently.)	§ 1.16(e)	can be paid
[☑ Enc	Josed		
	d	Filing fee	\$	786.00
	⊡⁄	Recording assignment (\$40.00; 37 C.F.R. § 1.21(h)) (See attached "COVER SHEET FOR ASSIGNMENT ACCOMPANYING NEW APPLICATION".)	\$	40.00
		Petition fee for filing by other than all the inventors or person on behalf of the inventor where inventor refused to sign or cannot be reached (\$130.00; 37 C.F.R. §§ 1.47 and 1.17(i))	\$	
		For processing an application with a specification in a non-English language (\$130.00; 37 C.F.R. §§ 1.52(d) and 1.17(k))	\$	
		Processing and retention fee (\$130.00; 37 C.F.R. §§ 1.53(d) and 1.21(l))	\$	····
		Fee for international-type search report (\$40.00; 37 C.F.R. § 1.21(e))	\$	
NOTE:	failing to 37 C.F.I either th	R. § 1.21(I) establishes a fee for processing and retaining any application pursuant to 37 C.F.R. § 1.53(f) and the second second in the sense of the second in the sense of the second in the sense of the processing and retention for year from notification under § 53(f).	is, as well a fit of a prior	s the changes to U.S. application,
		Total fees enclosed	\$826	5.00
14. M		of Payment of Fees		
(☑ Che	ck in the amount of \$826.00		
		erge Account No	in the	amount of
	A d	uplicate of this transmittal is attached.		
NOTE:	Fees she § 1.22(t	ould be itemized in such a manner that it is clear for which purpos s).	e the fees ar	e paid. 37 C.F.R.

(New Application Transmittal [4-1]—page 8 of 11)

is to another small entity.

15. A	uthorization to Charge Additional Fees
WARN	ING: If no fees are to be paid on filing, the following items should not be completed.
WARN	ING: Accurately count claims, especially multiple dependent claims, to avoid unexpected high charges, if extra claim charges are authorized.
6	The Commissioner is hereby authorized to charge the following additional fees by this paper and during the entire pendency of this application to Account No. 03-3420 :
	☑ _ 37 C.F.R. § 1.16(a), (f) or (g) (filing fees)
	37 C.F.R. § 1.16(b), (c) and (d) (presentation of extra claims)
NOTE:	Because additional fees for excess or multiple dependent claims not paid on filing or on later presentation must only be paid or these claims cancelled by amendment prior to the expiration of the time period set for response by the PTO in any notice of fee deficiency (37 C.F.R. § 1.16(d)), it might be best not to authorize the PTO to charge additional claim fees, except possibly when dealing with amendments after final action.
	37 C.F.R. § 1.16(e) (surcharge for filing the basic filing fee and/or declaration on a date later than the filing date of the application)
	☐ 37 C.F.R. § 1.17(a)(1)–(5) (extension fees pursuant to § 1.136(a)).
	☐ 37 C.F.R. § 1.17 (application processing fees)
NOTE:	" A written request may be submitted in an application that is an authorization to treat any concurrent or future reply, requiring a petition for an extension of time under this paragraph for its timely submission, as incorporating a petition for extension of time for the appropriate length of time. An authorization to charge all required fees, fees under § 1.17, or all required extension of time fees will be treated as a constructive petition for an extension of time in any concurrent or future reply requiring a petition for an extension of time under this paragraph for its timely submission. Submission of the fee set forth in § 1.17(a) will also be treated as a constructive petition for an extension of time in any concurrent reply requiring a petition for an extension of time under this paragraph for its timely submission." 37 C.F.R. § 1.136(a)(3).
	☐ 37 C.F.R. § 1.18 (issue fee at or before mailing of Notice of Allowance, pursuant to 37 C.F.R. § 1.311(b))
NOTE:	Where an authorization to charge the issue fee to a deposit account has been filed before the mailing of a Notice of Allowance, the issue fee will be automatically charged to the deposit account at the time of mailing the notice of allowance. 37 C.F.R. § 1.311(b).
NOTE:	37 C.F.R. § 1.28(b) requires "Notification of any change in status resulting in loss of entitlement to small entity status must be filed in the application prior to paying, or at the time of paying, the issue fee " From the wording of 37 C.F.R. § 1.28(b), (a) notification of change of status must be made even if the fee is paid as "other than a small entity" and (b) no notification is required if the change

(New Application Transmittal [4-1]—page 9 of 11)

16. Instructions as to Overpayment

·	saucaciic us is croipi	1,110111
NOTE:	a reasonable time, nor will the be returned by check or, if re	o dollars or less will not be returned unless specifically requested within payer be notified of such amounts; amounts over twenty-five dollars may equested, by credit to a deposit account." 37 C.F.R. § 1.26(a).
Ŀ	Credit Account No	05 5420
] Refund	

Reg. No. 31,945

Tel. No. (502) 589-4215

Customer No.

SIGNATURE OF PRACTITIONER

Scott R. Cox

(type or print name of attorney)

400 West Market St., Suite 2200

P.O. Address

Louisville, KY · 40202

(New Application Transmittal [4-1]-page 10 of 11)

Incorporation by reference of added pages
(check the following item if the application in this transmittal claims the benefit of prior U.S. application(s) (including an international application entering the U.S. stage as a continuation, divisional or C-I-P application) and complete and attach the ADDED PAGES FOR NEW APPLICATION TRANSMITTAL WHERE BENEFIT OF PRIOR U.S. APPLICATION(S) CLAIMED)
 Plus Added Pages for New Application Transmittal Where Benefit of Prior U.S Application(s) Claimed
Number of pages added
☐ Plus Added Pages for Papers Referred to in Item 4 Above
Number of pages added
Plus added pages deleting names of inventor(s) named in prior application(s) who is/are no longer inventor(s) of the subject matter claimed in this application
/ Number of pages added
Plus "Assignment Cover Letter Accompanying New Application"
Number of pages added <u>seven (7)</u>
Statement Where No Further Pages Added
(if no further pages form a part of this Transmittal, then end this Transmittal with this page and check the following item)
☐ This transmittal ends with this page.

5

P-1000

Title of Invention

PACKAGING CONTAINER FOR ELECTRONIC COMPONENTS

Background of Invention

1. Field of Invention.

This invention relates to packaging containers for electronic components. In particular, this invention relates to a packaging container for integrated circuits, wherein the composition of the cover for that packaging container includes a desiccating material electrostatic charge dissipating and / or anti-static In addition, this invention relates to a material. packaging container for integrated circuits, wherein the composition of the cover for that packaging container includes a desiccating material, an electrostatic charge dissipating and / or anti-static material and a humidity indicating system.

2. Prior Art.

Electronic components, such as integrated circuits ("IC"), are conventionally shipped from a factory to the user in large quantities. To protect these ICs during transportation, they are generally secured in special trays. Sections CO-027 - CO-032 and CO-034, and sections CS-002 - CS-008 of JEDEC publication, JEP95, contain outlines and specifications for standardized thin and thick matrix trays

5

for various IC types.

Plastic integrated circuit devices are susceptible to moisture due to the permeable nature of their plastic components. It is well known that ICs, which have been contaminated by high levels of moisture, may not be useful. Mechanical failure of such moisture contaminated ICs often leads to the subsequent failure of the device which contains the IC due to thermal and mechanical stress. Accordingly, exposure of ICs to moisture should be limited.

For specialized types of packaging for ICs, refer to U.S. 4,971,196, U.S. 5,095,626, U.S. 5,293,996 and U.S. 5,295,297. Each of the packaging containers disclosed by these patents incorporates a moisture indicator device into the packaging container, which device is secured to the inside surface of the container. See specifically Figures 7 and 10 of these patents.

Specifically, U.S. Patent No. 5,293,996 discloses a packaging container for integrated circuits containing an observation window. The container is divided into three sections, wherein one of those sections contains a compartment (11) housing a humidity indicator device (16). The humidity indicator device (16) is preferably a humidity indicator card. As best understood the card is merely placed within the compartment for viewing. The composition

20

5

of the packaging material of the compartment containing the humidity indicator card is a transparent plastic which permits the moisture indicator card to be viewed from outside of the packaging container.

U.S. Patent No. 5,318,181 discloses compartmentalized humidity sensing indicators. These humidity sensing indicators are produced on a tape reel and are secured to the inside surface of a continuous strip of humidity indicators.

2,446,361 discloses No. а Patent U.S. indicating moisture adsorbent product secured to packaged goods. The product comprises a container (A) onto which is secured a receptacle (B). Contained within the receptacle (B) is a desiccant (C). The receptacle (B) is transparent and may be formed from plastic materials. It is screwed into a threaded mounting apparatus which is also secured to the container. It is comprised of a cylindrical wall (16), closed top (17) and a perforated bottom (18). receptacle (B) is secured in place to the package by a collar (20) and a locking ring (22) containing threads (24, The receptacle (B) may be screwed in place using one of two different designs as disclosed in Figures 2 and 3 of the patent.

See also U.S. Patent No. 5,238,648 which discloses a

20

5

view port in packaging through which can be viewed an oxygen indicator device.

In addition to their susceptibility to moisture, ICs can also be damaged by static electricity. Therefore, it is important that the packaging for such electronic components also be resistant to electrostatic charge. This resistance should be present in the tray on which the ICs are stored as well as in the moisture-proof bag in which the tray is shipped. A laminated packaging system for ICs, which is resistant to static charge is disclosed in U.S. 5,136,827 and U.S. 4,568,416.

It is well known that electronic components are also sensitive to particles and dust. Therefore, manufacturing and assembly of electronic devices is performed in clean rooms of class 100 - 10.

Current packaging products which are used to ship integrated circuits still exhibit deficiencies, including limitations caused by the composition of the packaging material. Conventionally, the packaging material used for shipping integrated circuits is opaque, thus preventing easy inspection of conventional humidity indicator cards which are contained within the packaging unless the packaging material is breached. In certain new packaging materials, the composition of the surface of the packaging is different

20

5

from the composition of the remaining portion of the packaging that is adjacent to the humidity indicator so that the humidity indicator card can be viewed from outside of the packaging.

In addition, the method for attachment of the humidity indicator device to the inside surface of the packaging material is often not practical.

Further, packaging products for shipping integrated circuits often must include desiccant products because of the sensitivity of the integrated circuits to moisture. Several plastic materials which may be used for packaging produced which have incorporated moisture absorbing products, such as desiccating materials, into their structure. For example, U.S. Patent No. 5,911,937 discloses a product made from 30 to 80 percent desiccant, 20 to 40 percent thermoplastic and 5 to 20 percent of a channeling agent, wherein the channeling agent includes any hydrophillic material which is miscible with a polymer-based matrix upon melt mixing to form the channeled structure. These compounds preferably include polar compounds having at least several hydroxy groups, such as polyglycols. desiccants that can be incorporated within this plastic material include anhydrous salts, molecular sieves, silica gels, clays and starches. See also WO 96/33108.

15

20

A number of other plastic materials have been produced into which desiccating products have been incorporated. example, U.S. Patent No. 5,078,909 discloses a moisture absorbent product comprising 100 parts by weight of a thermoplastic resin and 5 to 400 parts of a desiccant. U.S. Patent No. 5,432,214 discloses a plastic product containing a desiccant comprising 50 - 80% of a thermoplastic or thermosetting product, 20 - 50% of a dehydrating agent, 2 -8% of an elastomer and 1 - 4% fibers. EP 432,438 discloses a desiccating plastic product comprising 100 parts of an absorbent particles mixed with 10 to 50 parts of a plastic particle and a reinforcing fiber. U.S. Patent No. 4,061,807 discloses a desiccating product containing 60 to 95 parts of absorbent granules mixed with 50 to 40 parts of a Patent No. 5,591,379 U.S. thermoplastic particles. discloses a coating or adhesive material which is placed on packaging for micro-electronic devices. A desiccant product is dispersed in the binder to form the coating or adhesive. The binder may include a number of polymers.

No. 4,013,566 discloses a desiccant Patent combined with a thermoset material. U.S. Patent No. 4,665,050 discloses a desiccant that is embedded in a U.S. Patent No. plastic without melting the plastic. 3,245,946 discloses a desiccant incorporated into a rubber

5

product for absorbing the moisture contained within the rubber product. U.S. Patent Nos. 4,792,484 and 4,407,897 disclose the use of EVOH copolymers with particular products including conventional desiccant materials. See also U.S. Patent Nos. 5,496,397 and 5,401,706.

U.S. Patent No. 5,702,508 discloses a moisture removing device comprising a ceramic shell with a plurality of parallel openings. The openings form elongated structure surfaces adapted to be in contact with moisture laden air moving through the openings. The surfaces have desiccant capabilities.

U.S. Patent No. 4,665,050 discloses a self-supporting structure wherein 1 to 7 percent polymer is mixed with absorbent particles to form a sorbent product. U.S. Patent No. 4,427,992 discloses a desiccant for semi-conductor products which may be applied in liquid form and consist of ethyl-alcohol, ethyl-acetate water and a source of boron, alumina or phosphorous and organic silane.

Finally, DE 4,013,799 discloses an insert for containers, particularly for medicines and semi-luxury consumer goods, wherein a granular drying agent is embedded in plastic.

As referenced above, integrated circuits are particularly susceptible to moisture and can also be damaged

5

by static electricity. Further, these components are particularly sensitive to dust. Accordingly, in the prior art integrated circuits have been prepared for shipping using a complicated and expensive process which includes at least the following process steps:

- a) inserting the integrated circuits into trays;
- b) baking the integrated circuits dry on the trays;
- c) stacking the trays on top of each other;
- d) covering the tray stack with a tray cover;
- e) inserting the covered tray stack in a moisture and water-proof bag;
- f) inserting desiccant bags into the moisture-proof bag;
- g) placing a humidity indicator card into the bag; and
 - h) sealing the bag.

An alternative procedure included at least the following steps:

- a) baking the integrated circuits dry separately from the packing trays;
- b) inserting the dried integrated circuits into the trays;
 - c) stacking the trays on top of each other;
 - d) covering the tray stack with a tray cover;

5

- e) inserting the covered tray stack in a moisture and water-proof bag;
- f) inserting desiccant bags into the moisture-proof bag;
- g) placing a humidity indicator card into the bag; and
 - h) sealing the bag.

In addition to the fact that this process is complicated, labor-intensive and time-intensive, the integrated circuits are protected from moisture only after the moisture-proof bag is sealed. Integrated circuits can still absorb moisture at any time from their original baking until the sealing of the bag.

Another disadvantage of the prior art processes is that the integrated circuits are also exposed to dust for a greater period of time. This dust may even include generated dust from the desiccant bags themselves.

Accordingly, it is an object of this invention to prepare a packaging container for electronic components which reduces the level of moisture within the container during shipment.

It is still further object of the invention to disclose a packaging container for electronic components, wherein the composition includes a desiccant product.

5

It is still further object of the invention to disclose a packaging container for electronic components which incorporates an electrostatic charge dissipating and/or anti-static material into the composition of the packaging container.

It is still further object of the invention to disclose a packaging container for integrated circuits which produces less dust and other particulate matter during packaging and shipment.

It is still further object of the invention to utilize a process for loading electronic components that has fewer steps and reduces the time and expense of the packaging process.

These and other objects and features of the present invention will become apparent to those skilled in art from a consideration of the following detailed description, drawings and claims. The description along with the accompanying drawings provides a selected example of the construction of the device and its process of manufacturing to illustrate the invention.

Summary of the Invention

In accordance with the present invention there is provided a packaging container for electronic components, which components are sensitive to humidity, which includes

5

trays for holding the electronic components, and

a tray cover, whose composition comprises a plastic material, an electrostatic charge dissipating and/or antistatic material and a desiccant for absorbing moisture contained or penetrating into the packaging container.

Alternatively, the present invention provides a packaging container for electronic components, which components are sensitive to humidity, which includes

trays for holding electronic components,

a tray cover, whose composition comprises a plastic material, an electrostatic charge dissipating and/or antistatic material and a desiccant for absorbing moisture contained or penetrating into the packaging container during shipment, and

a humidity indicating system secured to the tray cover for determining the humidity level within the packaging container.

The present invention further includes the packaging container discussed above placed within a moisture-proof barrier bag for shipment.

The present invention further includes a process for the filling and shipping of a packaging container with integrated circuits comprising

introducing integrated circuits into shipping trays;

5

baking the integrated circuits while in the trays to remove moisture;

securing a tray cover onto a stack of the baked trays, wherein the tray cover is comprised of a plastic material, an electrostatic charge dissipating and/or anti-static material and a desiccant for absorbing moisture contained or penetrating into the packaging container; and

placing the covered tray stack containing integrated circuits within a moisture-proof barrier bag.

Alternatively, the present invention includes a process for the filling and shipping of a packaging container with the integrated circuits comprising

introducing dry, baked integrated circuits into
shipping trays;

securing a tray cover onto a stack of the trays, wherein the tray cover is comprised of a plastic material, an electrostatic charge dissipating and/or anti-static material and a desiccant for absorbing moisture contained or penetrating into the packaging container; and

placing the covered tray stack containing integrated circuits within a moisture-proof barrier bag.

Brief Description of the Drawings

This invention will now be described with reference to the accompanying drawings in which

5

Figure 1 is the packaging container of the present invention.

Figure 2 is the packaging container of the present invention into which has been incorporated a humidity indicator card.

Figure 3 is a prior art system for shipment of integrated circuits.

Figure 4 is a top view of the tray cover of the packaging container of Figure 1.

Figure 5 is a top view of a humidity indicator disk and clear plastic disk which are mounted into the tray cover of Figure 4.

Figure 6 is a top view of an individual tray with an integrated circuit placed thereon.

Figure 7 is a top view of a stack of trays.

Detailed Description of the Preferred Embodiment

Electronic components, such as semi-conductor chips or integrated circuit chips, after manufacture and prior to utilization, are temporarily stored using a number of different storage systems. Current dry packing practices involve baking such electronic components until dry, placing them into a dry pack with desiccant bags and humidity indicator cards, sealing the bag immediately and shipping the sealed bag to the customer.

5

Prior art packaging containers (110) as shown in Figure were comprised of stacks of trays (120) and a tray cover (130). The packaging container (110), a humidity indicator device (140) to determine the moisture content of the air within the barrier bag (150), and desiccant bags (160) were placed in a barrier bag (150).

The components of the packaging container (10) of the present invention as shown in Figures 1 and 2 contain fewer components than the packaging container (110) of the prior art as shown in Figure 3. Prior to packaging, the electronic components, such as integrated circuits (22), are first placed on or within an individual tray (21) as shown in Figure 6. Any reasonable design for these trays (21) may be utilized to secure the integrated circuits during transport. However, the design of standardized trays has been established under the JEDEC tray convention, according to JEP 95.

A tray cover (30) of the invention is designed to cover the stacked trays (20). The tray cover (30) is manufactured from at least one thermoplastic or thermosetting plastic material, at least one desiccant material and preferably at least one material that contains electrostatic discharge or anti-static properties. The tray cover (30) may also contain one or more elastomers, fibers, channeling agents,

5

processing aids, stabilizers and pigments, as desired.

Well known plastic materials may be used to form the cover (30) include polyethylene, ethylene copolymers (e.g. polypropylene, polybuten-1, polyisobutylene, polyvinylchloride, vinylchloride copolymers, polyvinylidene chloride, polystyrene, styrene copolymers, cellulose derivatives, polyamide, polycarbonate, polyoxymethylene, polyethyleneterephthalate, polybutyleneterephthalate, copolyester, polyphenylenoxides, polymethymethacrylate, copolymers, flourine containing polymers, acrvlate polyphenylenesulphide, polyarylsulphones, polyaryletherketones, polyetherimids, polyimids, thermoplastic elastomers, polyurethanes, phenol resins, melamine resins, urea resins, epoxy resins and unsaturated polyester resins. Combinations of these plastic products may also be used to form the cover (30). In a preferred (30) is prepared form a embodiment the tray cover polypropylene material such as Moplen EPL 31 UA copolymer, produced by Montell.

A desiccant product is next incorporated into the thermoplastic and/or thermosetting plastic material. The desiccant product may be one or more selected form the groups of desiccating agents such as silica gel, a desiccant clay, activated alumina, calcium oxide, barium oxide,

5

natural or synthetic zeolites (including molecular sieve compounds) or the like, or deliquescent salts such as magnesium sulfate, calcium chloride, aluminum chloride, lithium chloride, calcium bromide, zinc chloride, or the like. In a preferred embodiment, a molecular sieve such as NK 10 AP, produced by Ceca, is incorporated into the plastic material.

The composition for the tray cover (30) also preferably includes a material which introduces electrostatic charge dissipating and/or anti-static properties to the plastic material, and is selected from the group consisting of carbon products, anionic surfactants, cationic surfactants, amines, amides, ethoxylated fatty amines, ethoxylated fatty amides and hydrophilic graft copolymers. In a preferred embodiment, a carbon black such as Printex XE2, produced by Degussa, is incorporated into the plastic material.

Other materials may also be incorporated into the composition of the tray cover (30) including elastomers, such as Kraton G 1650, a styrene-thylene-butadiene-styrene copolymer (SEBS), produced by Shell.

In a preferred embodiment the composition of the tray cover (30) is preferably a polypropylene plastic material comprising from about 20 to about 60 percent of the composition of the tray cover (30), preferably from about 30

5

to about 50 percent. Preferably the desiccant material is a molecular sieve, such as NK 10 AP produced by CECA, and comprises from about 30 to about 80 percent of the composition of the tray cover (30), preferably from about 40 to about 65 percent. The electrostatic charge dissipating material comprises from about 2 to about 10 percent of the composition of the tray cover, preferably from about 3 to about 8 percent, with the remaining components formed from other conventional additives, such as elastomers, processing aids and pigments. All percentages are by weight.

The process used for forming the tray cover includes the following steps:

- a) The polypropylene and SEBS are fed into the main feeder of an extruder and heated.
- b) The molecular sieve and carbon black products are fed into the extruder via a lateral feeder.
- c) The mixture is degassed several times, preferably under vacuum.
- d) The mixture is then pressed through a die, cooled and pelletized.
- e) The pelletized material is melted, and the tray cover is injection molded using conventional procedures.

Alternatively, the tray cover (30) may be formed by thermaforming or other conventional means of forming plastic

20

5

material.

The tray cover (30) may be formed in any conventional shape or structure that covers the trays (20) for the integrated circuits. Notwithstanding, it preferably complies with the standards set by JEDEC, namely JEPGS.

During the formation of the tray cover (30), an opening is preferably formed in the cover (30). This opening is designed to hold the humidity indicator device (40). The size and shape of this opening depends upon which humidity indicator device (40) is secured to the tray cover (30).

In a preferred embodiment the opening for the humidity indicator (40) is circular. Into this circular opening is placed a clear plastic circular disk (42) as shown in Figures 4 and 5. This clear plastic circular disk (42) can be manufactured from any clear plastic material, preferably from copolyesters like Durastar DS2000 produced by Eastman Chemicals. This clear plastic circular disk (42) covers the opening to prevent water and water-vapor from passing into the interior of the packaging container (10).

disk (42) is the humidity indicator element (44). The humidity indicator element (44) is preferably formed from a hydrophilic blotter substrate onto which is placed a

Secured to the inside of the clear plastic circular

humidity indicator solution which readily discloses the

5

level of humidity in the air surrounding the disk (42) by changing its color depending on the level of humidity This substrate and humidity indicator solution are well known in the industry. The substrate is preferably blotter paper, for example, manufactured by Custom Paper. Preferably, the humidity indicating solution comprises a solution of cobalt chloride. The preferred cobalt chloride solution is also well known in the industry and hygroscopic in nature. It demonstrates different colors or different degrees of color based on the amount of moisture in the air surrounding the humidity indicator element (44). The humidity indicator solution is incorporated onto the humidity indicator substrate by conventional means.

Once the humidity indicator solution has been secured onto the substrate, the substrate is formed into the desired shape for use as the humidity indicator element (44). humidity indicator element (44) is preferably formed into a circular shape as shown on Figures 4 and 5.

In order to determine the level of humidity which is indicated by the color of the humidity indicator element (44), a conventional humidity comparison element (not shown) is preferably secured next to the humidity indicator The humidity comparison element, which is element (44). preferably formed from a material which is not affected by

5

the level of humidity present in the packaging container (10), is used to compare the level of the humidity shown on the humidity indicator element (44) against known levels of humidity shown by different colors on the humidity comparison element. The humidity comparison element of the preferred embodiment is preferably round with a circular opening cut into its middle.

The humidity indicator element (44) is preferably secured to the back of the humidity comparison element by conventional means, such as by an adhesive. By securing the humidity indicator element (44) to the humidity comparison element with a portion of the humidity indicator element (44) which is sensitive to humidity covering a circular opening in the middle of the humidity comparison element, it is easy for a viewer of this assembly to determine the relative humidity level within the container by merely comparing the color shown on the humidity indicator element (44) with the various colors referenced on the humidity comparison element. The size and shape of the humidity indicator element (44) and humidity comparison element can be altered from that shown in Figures 4 and 5. In addition, humidity comparison element single color may substituted for a multicolored humidity comparison element.

Once the electronic components to be shipped have been

placed within the packaging container (10), the humidity within that container can be readily checked merely by viewing through the clear plastic disk (42) that is secured to the inside surface of the packaging container (10). Any water vapor inside the packaging container (10) will contact with the humidity indicator element (42) and produce a change in its color which then discloses the moisture content of the air within the packaging container (10). By comparing the color of the humidity indicator element (42) with the color shown on the humidity comparison element, the level of humidity within the packaging container can be readily determined.

In the preferred embodiment the packaging container (10) is placed within a water-proof barrier bag (50). The composition of the water-proof packaging bags is preferably a multi-layer composite of polymer films and aluminum foil. In one preferred embodiment the water and vapor-proof packaging material is DRI-PAK® manufactured by Richmond Technologies.

20

In forming the packaging container (10) of the present invention, the trays (20) are first formed from conventional material. The tray cover (30) is then formed. In a preferred embodiment the tray cover (30) is produced from a plastic material, an electrostatic charge dissipating

20

material and/or anti-static material and a desiccating material, preferably a molecular sieve material as discussed above. An opening may then be cut into the cover (30). The humidity indicator device (40) including the humidity indicator element (44) and the circular disk (42) are then secured together by adhesive or other sealing systems. The humidity indicator device (40) is then secured through the opening to the surface of the packaging container (10) preferably on the inside surface. This humidity indicator device (40) seals the opening in the tray cover (30) completely.

The integrated circuits are then introduced into the trays (20) as shown in Figure 6, and the trays (20) are stacked on each other to form tray stacks (20) as shown in Figure 7. These tray stacks (20) with the integrated circuits are then baked to dry the integrated circuits and the tray cover (30) is placed over the tray stack (30) to close the tray stack. Once the tray cover (30) is closed onto the tray stack (20) to form the packaging container (10), the packaging container (10) is then inserted into the water and moisture-proof barrier bag (50) and the bag (50) is sealed.

Alternatively, the integrated circuits may be baked dry on separate carriers and introduced already dry into the

5

trays which are then stacked on each other to form a tray stack (20). The tray cover (30) is then placed over the tray stack (20). Once the tray cover (30) is closed onto the tray stack (20) in order to form the packaging container (10), the packaging container (10) is inserted into the water and moisture-proof barrier bag (50) and the bag (50) is sealed.

As stated above, the preferred tray cover (30) according to this invention already contains a humidity indicator device (40) as an integral part of its design. Alternatively, a tray cover (30) according to this invention without a humidity indicator device as an integral part of its design can be used. In this case a conventional humidity indicator device (140) is inserted into the water and moisture-proof bag (50) prior to sealing.

By using the tray cover (30) of the particular composition, according to the invention, several processing steps can be eliminated creating a faster process and decreasing the overhead costs. In addition, this new process reduces the time of potential exposure of the integrated circuits to moisture. Further, the problem of dust being present within the trays (20) is reduced if not eliminated as a result of the desiccant material being encapsulated within the tray cover (30). In addition, as

the desiccant material is already contained in the tray cover (30), no additional weight or volume from desiccant bags has to be added to the packaging container (10).

By having a humidity indicator device (40) secured into the cover (30) of the packaging container (10), the consumer of the integrated circuits can determine merely by looking at the humidity indicator element (44) whether the level of humidity within the packaging container (10) is too high. If so, the integrated circuits may be re-baked to lower the level of the moisture present therein.

It will be apparent for the foregoing that while particular forms of the invention have been illustrated and described, various modifications can be made without departing from the spirit and scope of the invention.

5

Claims

- 1. A packaging container for integrated circuits comprising
 - a tray for holding integrated circuits, and
- a tray cover, wherein the composition of the tray cover comprises a plastic material, an electrostatic dissipating charge material, and a desiccating material for adsorbing moisture contained within the packaging container.
- 2. The packaging container of Claim 1 further comprising a humidity indicator device secured to the tray cover, which indicator device determines a humidity level within the packaging container.
- 3. The packaging container of Claim 2 wherein the humidity indicator device is secured into an opening in the tray cover.
- 4. The packaging container of Claim 1 wherein the plastic material of the tray cover comprises a polypropylene.
- 5. The packaging container of Claim 2 wherein the humidity indicator device comprises a humidity indicator element and a system for securing the humidity indicator element to the tray cover.
- 6. The packaging container of Claim 5 wherein the humidity indicator element comprises a hydrophillic blotter

5

substrate onto which a humidity indicator solution has been placed.

- 7. The packaging container of Claim 6 wherein the humidity indicator solution comprises cobalt chloride.
- 8. The packaging container of Claim 2 wherein the humidity indicator device is secured to the tray cover using a clear, plastic disk mounted within the opening in the tray cover.
- 9. The packaging container of Claim 1 further comprising a water and moisture-proof barrier bag into which the tray is secured.
- 10. A packaging container for integrated circuits comprising
 - a tray for holding integrated circuits,
- a tray cover, wherein the composition of the tray cover comprises a plastic material, an electrostatic dissipating charge material, and a desiccating material for adsorbing moisture contained within the packaging container,
- a humidity indicator device secured to the tray cover for determining the humidity level within the packaging container; and
- a moisture-proof barrier bag into which the tray and the tray cover are placed.
 - 11. The packaging container of Claim 10 wherein the

5

humidity indicator device is secured into an opening in the tray cover.

- 12. The packaging container of Claim 10 wherein the composition of the tray cover further comprises an antistatic material.
- 13. The packaging container of Claim 10 wherein the plastic material of the tray cover comprises a polypropylene.
- 14. The packaging container of Claim 10 wherein the humidity indicator device comprises a humidity indicator disk and a system for securing the humidity indicator disk to the tray cover.
- 15. The packaging container of Claim 14 wherein the humidity indicator disk comprises a hydrophillic blotter substrate onto which a humidity indicator solution has been placed.
- 16. The packaging container of Claim 15 wherein the humidity indicator solution comprises cobalt chloride.
- 17. The packaging container of Claim 11 wherein the humidity indicator device is secured to the tray cover using a clear plastic disk mounted within the opening in the tray cover.
- 18. A process for filling and shipping of a packaging container containing integrated circuits comprising

25

5

introducing integrated circuits into a tray,

baking the integrated circuits while in the tray to reduce the water content in the integrated circuits,

securing a tray cover over the tray, wherein the tray cover is comprised of a plastic material, an electrostatic charge dissipating material and a desiccating material for absorbing moisture contained within the packaging container; and

placing the covered tray containing integrated circuits within a moisture-proof barrier bag.

19. A process for filling and shipping of a packaging container containing integrated circuits, comprising

introducing dry, baked integrated circuits into a shipping tray,

securing a tray cover over the tray, wherein the tray cover is comprised of a plastic material, an electrostatic charge dissipating material and a desiccating material for absorbing moisture contained within the packaging container; and

placing the covered tray containing dry baked integrated circuits within a moisture-proof barrier bag.

- 20. The process of Claim 18 wherein the tray cover further comprises a humidity indicator device.
- 21. The process of Claim 19 wherein the tray cover further comprises a humidity indicator device.

Abstract

A packaging container for electronic components, particularly integrated circuits, which includes a tray into which the integrated circuits can be secured, a tray cover which is secured onto the tray, wherein the tray cover is composed of a plastic material, a desiccating material and an electrostatic dissipating product. The tray cover may further include a humidity indicating system incorporated into the tray cover. The packaging container may also be placed within a water and moisture-proof barrier bag for shipment purposes.

SRC:sb:dg C:\WP\PAT\P1000 93420 8-28-00

Figure 1

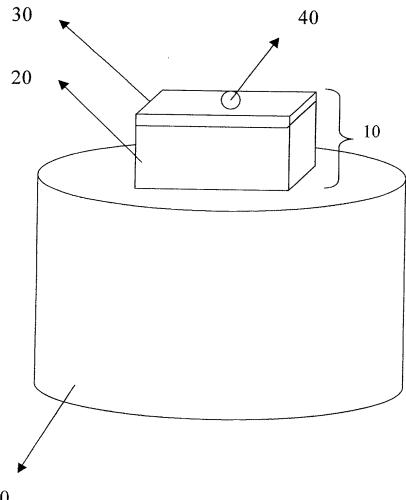


Figure 2

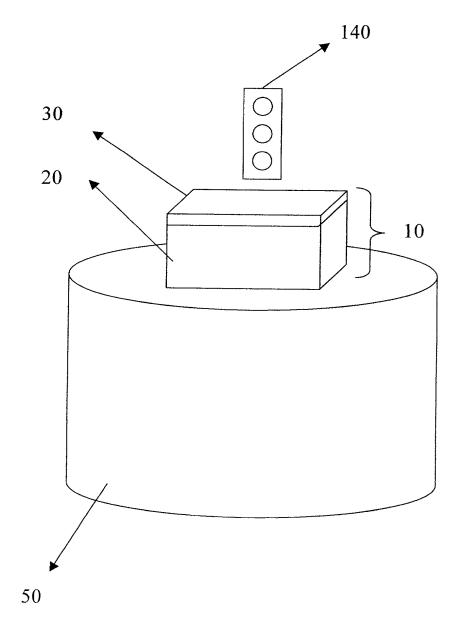


Figure 3: Prior art

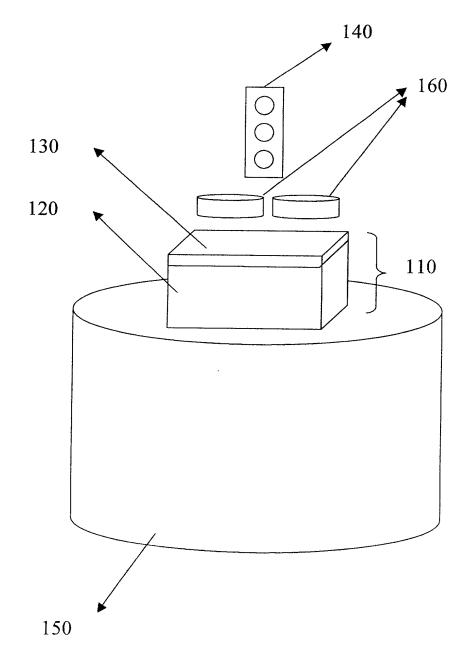


Figure 4:

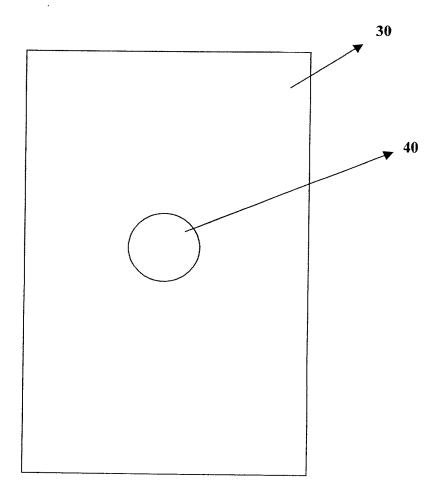
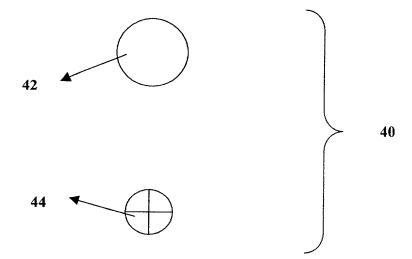
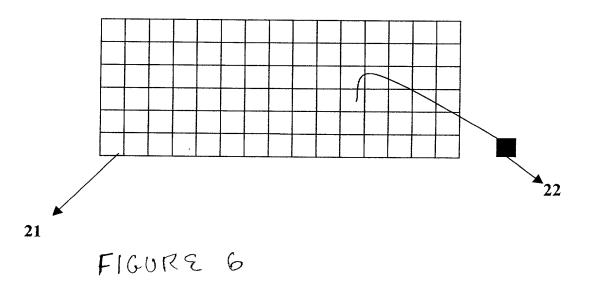


Figure 5:





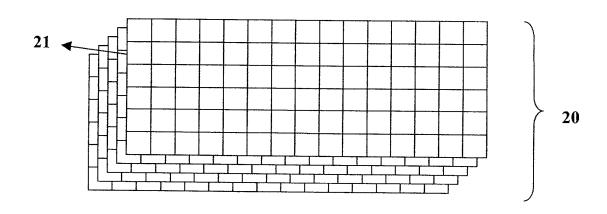


FIGURE 7

Practitioner's Docket No. P-1000	PATENT
COMBINED DECLARATION AND POWER	OF ATTORNEY
(ORIGINAL, DESIGN, NATIONAL STAGE OF PCT, SUPF CONTINUATION, OR C-I-P)	PLEMENTAL, DIVISIONAL,
As a below named inventor, I hereby declare that:	
TYPE OF DECLARATION	
This declaration is of the following type:	
(check one applicable item belo	w)
☑ original.	
☐ design.	
☐ supplemental.	
NOTE: If the declaration is for an International Application being f continuation-in-part application, do <u>not</u> check next item; check	iled as a divisional, continuation or appropriate one of last three items.
national stage of PCT.	
NOTE: If one of the following 3 items apply, then complete and also atta CONTINUATION OR C-I-P.	
NOTE: See 37 C.F.R. § 1.63(d) (continued prosecution application) for u declaration in the continuation or divisional application being fit the inventors named in the prior application.	se of a prior nonprovisional application led on behalf of the same or fewer of
☐ divisional.	
continuation.	
NOTE: Where an application discloses and claims subject matter not continuation or divisional application names an inventor not continuation-in-part application must be filed under 37 C.F.R. § — nonprovisional application).	ot named in the prior application, a
continuation-in-part (C-I-P).	
INVENTORSHIP IDENTIFICATION	TION
WARNING: If the inventors are each not the inventors of all the claims the ownership of all the claims at the time the last claimed inv	s, an explanation of the facts, including rention was made, should be submitted.
My residence, post office address and citizenship are as s I believe that I am the original, first and sole inventor (if on an original, first and joint inventor (if plural names are liste that is claimed, and for which a patent is sought on the in	ly one name is listed below) or Id below) of the subject matter
TITLE OF INVENTION	
Packaging Container for Electronic C	omponents
	,
(Declaration and	Power of Attorney [1-1]-page 1 of 7)

SPECIFICATION IDENTIFICATION

the specification of which:			
(comple	ete (a), (b), or (c))		
(a) is attached hereto.			
NOTE: "The following combinations of informations filling date with a specification are accept with any one of the items below will be 37 CFR 1.63:	NOTE: "The following combinations of information supplied in an oath or declaration filed on the application filing date with a specification are acceptable as minimums for identifying a specification and compliance with any one of the items below will be accepted as complying with the identification requirement of		
"(1) name of inventor(s), and reference to an attached specification which is both attached to the oath or declaration at the time of execution and submitted with the oath or declaration on filing;			
"(2) name of inventor(s), and or	attomey docket number which was on the specification as filed;		
"(3) name of inventor(s), and	d title which was on the specification as filed."		
Notice of July 13, 1995 (11			
	, as Serial No. 0 /		
and was amended on	(if applicable).		
NOTE: Amendments filed after the original papers are deposited with the PTO that contain new matter are not accorded a filing date by being referred to in the declaration. Accordingly, the amendments involved are those filed with the application papers or, in the case of a supplemental declaration, are those amendments claiming matter not encompassed in the original statement of invention or claims. See 37 CFR 1.67. NOTE: "The following combinations of information supplied in an oath or declaration filed after the filing date are acceptable as minimums for identifying a specification and compliance with any one of the items			
below will be accepted as complying with the identification requirement of 37 CFR 1.63: "(1) name of inventor(s), and application number (consisting of the series code and the serial			
number; e.g., 08/123,456);			
"(2) name of inventor(s), serial number and filing date; "(3) name of inventor(s) and attorney docket number which was on the specification as filed;			
"(4) name of inventor(s), title which was on the specification as filed and filing date;			
"(5) name of inventor(s), title which was on the specification as filed and reference to an attached specification which is both attached to the oath or declaration at the time of execution and submitted with the oath or declaration; or			
"(6) name of inventor(s), title which was on the specification as filed and accompanied by a cover letter accurately identifying the application for which it was intended by either the application number (consisting of the series code and the serial number; e.g., 08/123,456), or serial number and filing date. Absent any statement(s) to the contrary, it will be presumed that the application filed in the PTO is the application which the inventor(s) executed by signing the oath or declaration."			
Notice of July 13, 1995 (1	177 O.G. 60), M.P.E.P. § 601.01(a), 6th ed., rev. 3.		
	imed in PCT International Application No. _, filed on and as		
	19 on (if any).		

SUPPLEMENTAL DECLARATION (37 C.F.R. § 1.67(b))

(complete the following where a supplemental declaration is being submitted)			
☐ I hereby declare that the subject matter of the			
☐ attached amendment			
amendment filed on			
was part of my/our invention and was invented before the filing date of the original application, above-identified, for such invention.			
ACKNOWLEDGEMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR			
I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.			
I acknowledge the duty to disclose information, which is material to patentability as defined in 37, Code of Federal Regulations, § 1.56,			
(also check the following items, if desired)			
and which is material to the examination of this application, namely, information where there is a substantial likelihood that a reasonable Examiner would consider it important in deciding whether to allow the application to issue as a patent, and			
 in compliance with this duty, there is attached an information disclosure statement, in accordance with 37 CFR 1.98. 			
PRIORITY CLAIM (35 U.S.C. §§ 119(a)-(d))			
NOTE: "The claim to priority need be in no special form and may be made by the attorney or agent if the foreign application is referred to in the oath or declaration as required by § 1.63. The claim for priority and the certified copy of the foreign application specified in 35 U.S.C. 119(b) must be filed in the case of an interference (§ 1.630), when necessary to overcome the date of a reference relied upon by the examiner, when specifically required by the examiner, and in all other situations, before the patent is granted. If the claim for priority or the certified copy of the foreign application is filed after the date the issue fee is paid, it must be accompanied by a petition requesting entry and by the fee set forth in § 1.17(i). If the certified copy is not in the English language, a translation need not be filed except in the case of interference; or when necessary to overcome the date of a reference relied upon by the examiner; or when specifically required by the examiner, in which event an English language translation must be filed together with a statement that the translation of the certified copy is accurate." 37 C.F.R. § 1.55(a).			
I hereby claim foreign priority benefits under Title 35, United States Code, §§ 119(a)–(d) of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.			
(complete (d) or (e))			
(d) on such applications have been filed.			
(e) ☐ such applications have been filed as follows.			
NOTE: Where item (c) is entered above and the International Application which designated the U.S. itself claimed priority check item (e), enter the details below and make the priority claim.			
(Declaration and Power of Attorney [1-1]—page 3 of 7)			

PRIOR FOREIGN/PCT APPLICATION(S) FILED WITHIN 12 MONTHS (6 MONTHS FOR DESIGN) PRIOR TO THIS APPLICATION AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. § 119(a)–(d)

COUNTRY (OR INDICATE IF PCT)	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY UNDER 37	
			☐ YES	NO 🗆
			☐ YES	NO 🗆
			☐ YES	NO 🗆
			☐ YES	NO 🗆
			☐ YES	NO 🗆
PROVISIONAL A	APPLICATION NUMBER		FILING D	ATE
				
	I FOR BENEFIT OF EARL UNDER 35	IER US/PCT APPL	.ICATION	(S)
а	The claim for the benefit of ttached ADDED PAGES TO C TTORNEY FOR DIVISIONAL	COMBINED DECLARA	ATION AND	POWER OF

PART (C-I-P) APPLICATION.

ALL FOREIGN APPLICATION(S), <i>IF ANY,</i> FIL (6 MONTHS FOR DESIGN) PRIOR TO T	
NOTE: If the application filed more than 12 months from the filing the basis for this application entering the United States a divisional, or continuation-in-part, then also complete AD AND POWER OF ATTORNEY FOR DIVISIONAL, CONTIN of the prior U.S. or PCT application(s) under 35 U.S.C.	s (1) the national stage, or (2) a continuation, DED PAGES TO COMBINED DECLARATION IUATION OR C-I-P APPLICATION for benefit
POWER OF ATTORI	NEY
I hereby appoint the following practitioner(s) to pro- all business in the Patent and Trademark Office conn	
(list name and registration	number)
Scott R. Cox Reg. No. 31,945	
(check the following item, if	applicable)
I hereby appoint the practitioner(s) associate vided below to prosecute this application Patent and Trademark Office connected the	and to transact all business in the
Attached, as part of this declaration and poof the above-named practitioner(s) to accerepresentative(s).	
SEND CORRESPONDENCE TO	DIRECT TELEPHONE CALLS TO: (Name and telephone number)
Address Scott R. Cox LYNCH, COX, GILMAN & MAHAN, PSC 400 West Market, Suite 2200 Louisville, Kentucky 40202	Scott R. Cox LYNCH, COX, GILMAN & MAHAN, PSO (502) 589-4215
☐ Customer Number	

DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

SIGNATURE(S)

NOTE: Carefully indicate the family (or last) name, as it should appear on the filing receipt and all other documents.

Full name of sole or first	inventor	
Stefan	<u>o.</u>	Dick
(GIVEN NAME)	(MIDDLE INITIAL OR NAME)	FAMILY (OR LAST NAME)
Inventor's signature		
Date Aug 7-3 20	<u>ීරටි</u> Country of Citizenship	German
Residence 8204 Will	iam Moyers Ave, NE	
Post Office Address A1	buquerque, NM 87122	
		CARLA DUX
		7700
		/
Full name of second joint	linuantas Manu	
	<u> </u>	
Michelle (GIVEN NAME)	B. (MIDDLE INITIAL) OR NAME)	<u> Martin</u>
	(MIDDLE INITIALION NAME)	FAMILY (OR LAST NAME)
Inventor's signature	peace of a	
Date Hug 25 LOOK	Country of Citizenship	United States
Residence 2450 Vern	· ·	
Post Office Address Pa	<u> 1m Springs, CA 92262</u>	
Full name of third joint in	ventor, if any	
Roger		Nobilet
(GIVEN NAME)	(MIDDLE INITIAL OR NAME)	FAMILY (OR LAST NAME)
Inventor's signature	Moiler	
Date <u>08/24/00</u>	Country of Citizenship	Franco
	Country of Citizenship	Trance
	auregard	
Post Office Address $\underline{77}$	200 Torcy, France	

(Declaration and Power of Attorney [1-1]-page 6 of 7)

/	(check proper box(es) for any of the following added page(s) that form a part of this declaration)
Ø	Signature for fourth and subsequent joint inventors. Number of pages added
	* * *
	Signature by administrator(trix), executor(trix) or legal representative for deceased or incapacitated inventor. Number of pages added
	* * *
	Signature for inventor who refuses to sign or cannot be reached by person authorized under 37 CFR 1.47. Number of pages added
	* * *
	Added page for signature by one joint inventor on behalf of deceased inventor(s) where legal representative cannot be appointed in time. (37 CFR 1.47)
	* * *
	Added pages to combined declaration and power of attorney for divisional, continuation, or continuation-in-part (C-I-P) application.
	Authorization of practitioner(s) to accept and follow instructions from representative.
	* * *
	(if no further pages form a part of this Declaration, then end this Declaration with this page and check the following item)
	☐ This declaration ends with this page.

ADDED PAGE TO COMBINED DECLARATION AND POWER OF ATTORNEY FOR SIGNATURE BY FOURTH AND SUBSEQUENT INVENTORS

rull name of fourth joint in	ventor, if any	
Frederic		Bouvier
(GIVEN NAME)	(MIDDLE INITIAL OR NAME)	FAMILY (OR LAST NAME)
Inventor's signature	Thirte	
Date _08/24/00-	Country of Citizenship	France
Residence Petit cha	mp et grand pre	·
Post Office Address <u>38</u>	420 Revel, France	
Full name of fifth joint inve	ntor, if any	
(GIVEN NAME)	(MIDDLE INITIAL OF NAME)	FAMILY (OR LAST NAME)
Inventor's signature		
Date	Country of Citizenship	
Date	Country of Citizenship .	
Residence		
Post Office Address		
	V - 10 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	
		
Full name of sixth joint inve	entor, if any	
(GIVEN NAME)	(MIDDLE INITIAL OR NAME)	FAMILY (OR LAST NAME)
Inventor's signature		
Date	Country of Citizenship _	
Inventor's signature		
Date	Country of Citizenship _	
Residence		
Post Office Address		